

87654321

REV #
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REVISIONS
DESCRIPTION
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87654321

FABRICATION NOTES:

1. FABRICATE PCB IN ACCORDANCE WITH IPC-6012C, CLASS 2; PER IPC-6011. PCB SHALL BE MANUFACTURED USING IT180A OR EQUIVALENT WITH Et 4.

2. MATERIALS:

1. LAMINATE AND PREPREG (B-STAGE) TO BE IN ACCORDANCE WITH IPC-4101/126. (MIN.TG 170)

2. COPPER FOIL TO BE IN ACCORDANCE WITH IPC-MF-150. UNLESS OTHERWISE SPECIFIED, ALL COPPER WEIGHT FOR INNER SIGNAL LAYERS AND INNER PLANE LAYERS TO BE 350M (1 OZ.). FOR OUTER LAYERS 350M (1.0 OZ). COPPER WEIGHT IS TO BE CONSIDERED "FINISHED". THE COPPER FOIL THICKNESS TOLERANCES SHALL BE AS PER IPC 6012B TABLE NO.3-7 AND 3-8.

3. ALL HOLES SHALL BE LOCATED WITHIN 0.15MM DIAMETER OF TRUE POSITION. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.125MM.

4. BOW AND TWIST SHALL NOT EXCEED MORE THAN 0.75% OF THE DESIGN LENGTH.

5. CONDUCTOR WIDTH SHALL NOT BE LESS THAN 20% FROM ITS ORIGINAL DATA. INCREASE FOR MATCHING IMPEDANCE VENDOR SHALL TAKE APPROVAL FOR THE MODIFYING TRACE WIDTHS AND SPACING. TRACE WIDTH SHALL BE MEASURED ON THE SURFACE IN CONTACT WITH THE LAMINATE.

6. AUTOMATED OPTICAL INSPECTION OF ALL THE LAYERS IS REQUIRED.

7. FINISH:

1. ALL EXPOSED CONDUCTIVE PATTERN AREAS NOT COVERED WITH SOLDER MASK OR OTHER PLATING SHALL BE ENIG. ELECTROLESS NICKEL/IMMERSION GOLD. ELECTROLESS NICKEL SHALL BE 3-6 MICRONS. TYPICAL IMMERSION GOLD THICKNESS SHALL BE 0.04-0.06 MICRONS OF SOLDERABLE IMMERSION GOLD SURFACE.

2. APPLY LIQUID PHOTO IMAGEABLE SOLDER MASK PER IPC-9M-840, CLASS H, TO BOTH SIDES OF THE BOARD OVER BARE COPPER. VIA HOLES SHALL BE FILLED WITH NON CONDUCTIVE INK AND COVERED WITH SOLDER MASK. ONLY SOLDER MASK IMAGES THAT ARE 0.08(0.003") PER SIDE SHALL BE REDUCED IF REQUIRED. ALL OTHER SOLDER MASK IMAGES SHALL NOT BE ENLARGED. DEFAULT COLOUR OF SOLDER MASK SHALL BE GREEN.

3. SILKSCREEN SHALL BE WHITE, PERMANENT, ORGANIC, NON-CONDUCTIVE INK. THERE SHALL BE NO SILKSCREEN ON ANY SOLDERABLE COMPONENT PAD. CLIPPING OF SILK SCREEN SHALL BE ALLOWED IF THE SILK SCREEN FALLS ON SOLDERABLE AREA.

4. SURFACE AND VIA HOLES FINISH SHALL NOT BE LESS THAN 20UM (0.00079").

5. ALL HOLES SURROUNDED BY LAND <=0.010" SHALL BE COMPLIANT TO IPC6012, CLASS 2.

8. MARKING:

1. BOARD SHALL MEET THE REQUIREMENTS OF UL-796E WITH FLAMMABILITY RATING OF MINIMUM 94V-0. UL LOGO,UL FILE NUMBER, MANUFACTURER'S IDENTIFICATION AND DATE CODE LETTER SHALL BE RENDERED IN SILKSCREEN.

9. TEST REQUIREMENTS:

1. 100% NET LIST ELECTRICAL VERIFICATION USING MISTRAL SUPPLIED IPC-D-356 NET LIST FOR OPENS AND SHORTS.

10. THIEVING IS ALLOWED ONLY IN THE PANEL FRAME, NOT IN THE CIRCUIT AREA.

11. ALL VIA'S SHALL BE TENTED UNLESS OTHERWISE SPECIFIED.

12. TRACE IMPEDANCE SHALL BE +/-10% AS-PER IMPEDANCE SPECIFICATION TABLE.

13. FINISHED PCB THICKNESS SHALL BE 0.0615" +/-0.001.

14. MIN TRACE WIDTH/SPACING ON BOARD IS 0.003"/0.006".

15. ALL NON FUNCTIONAL PAD'S OF VIA'S AND PTH HOLES SHALL BE REMOVED.

100.15

LCD ADAPTER

COPY OF LCD ADAPTER

IMPEDANCE SPECIFICATIONS

SL#	TYPE	LAYER	TRACEWIDTH (Mils)	SPACING (Mils)	IMPEDANCE (Ohms)	REF LAYER
01	MICROSTRIP	L1/L4	7.5	NA	50	L2/L3
02	EDGE COUPLED MICROSTRIP	L4	5	7	100	L3

LAYER STACKUP

LAYER NAME	FINISHED Cu	X-SECTION	DIELECTRIC THICKNESS
PRIMARY SIDE SILKSCREEN			[INCHES]
PRIMARY SIDE SOLDERMASK			
L01 — PRIMARY SIDE	1oz.		0.0047
L02 — POWER-PLANE	1oz.		0.045
L03 — GROUND-PLANE	1oz.		0.0047
L04 — SECONDARY SIDE	1oz.		
SECONDARY SIDE SOLDERMASK			
SECONDARY SIDE SILKSCREEN			

SIGNATURES
LAYOUT BY VJC
REVIEWED BY ZA
APPROVED BY AMB

DATE
030918
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TEXAS INSTRUMENTS

PROC070

AM654x Rocktech RK101II01D LCD Adapter Board

SIZE
D

Rev
E3

SCALE: NONE

SHEET 1 OF 11